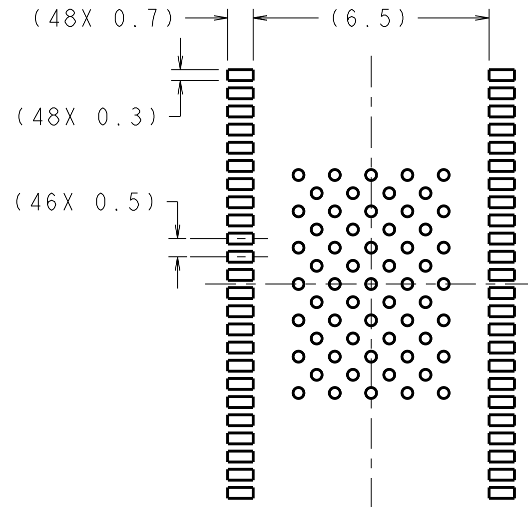
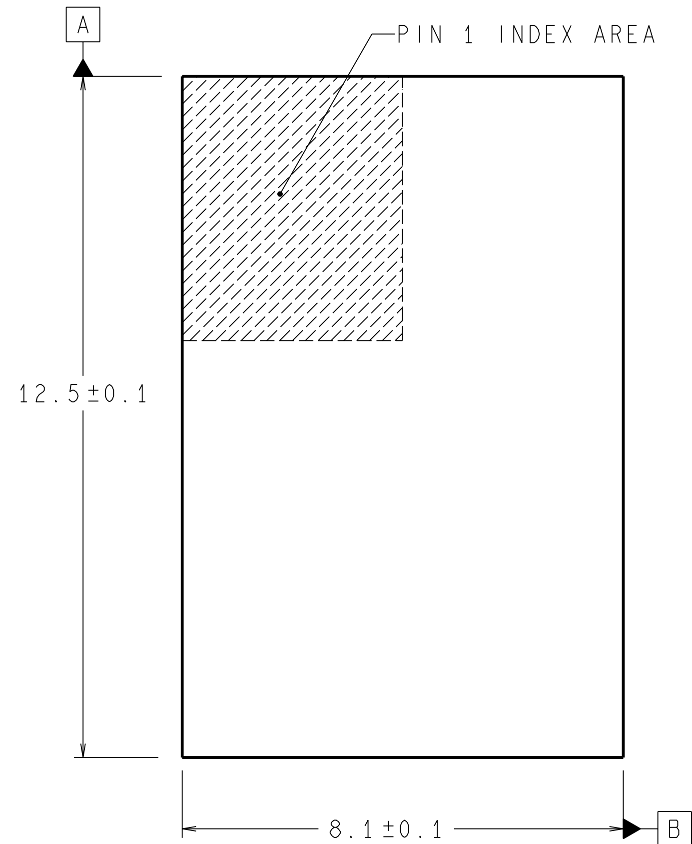
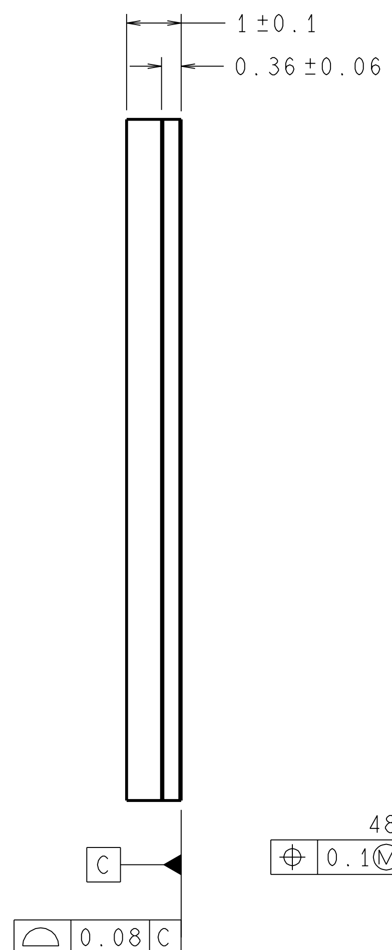
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12393	01/31/2000	TL/WL

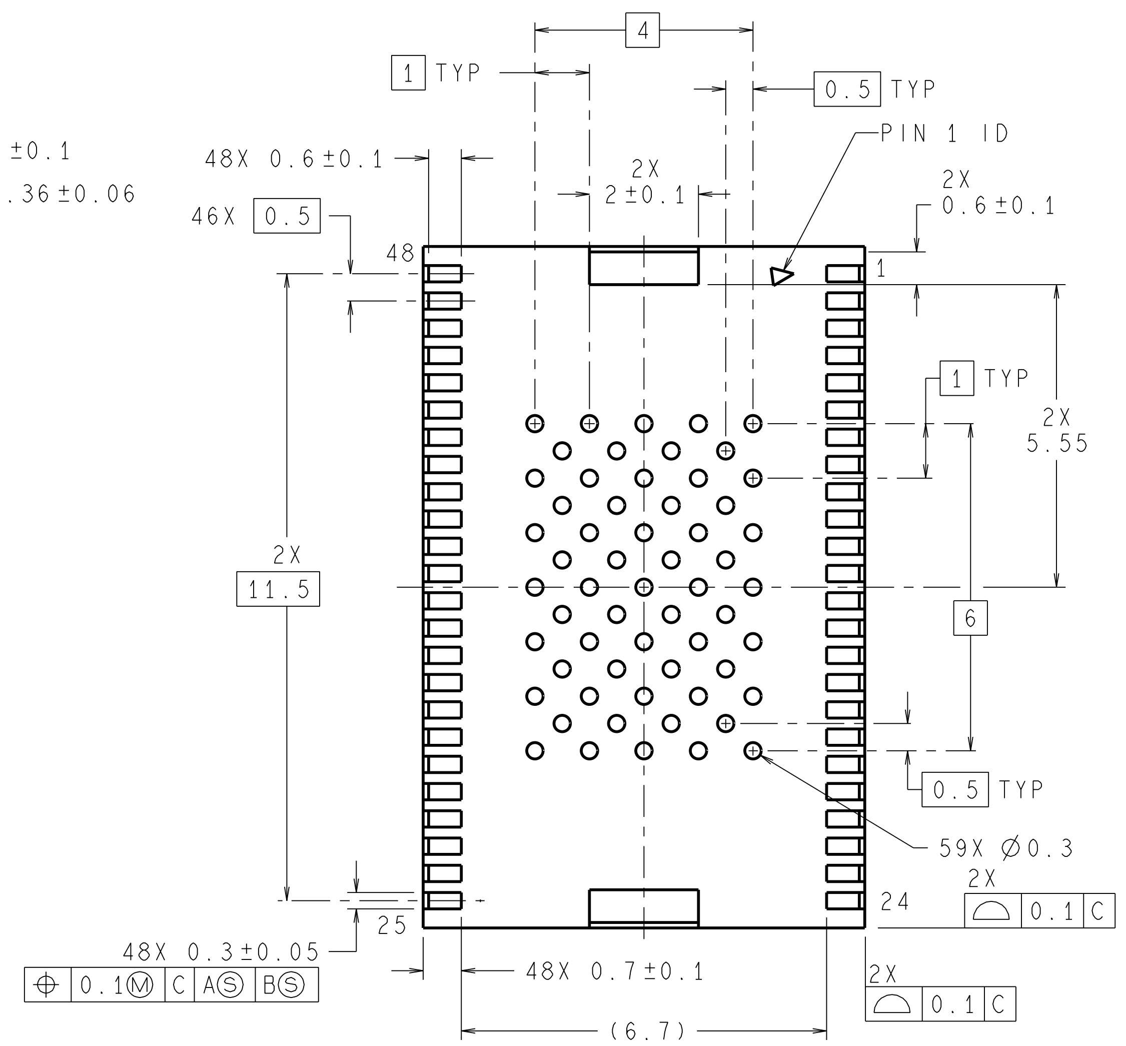


RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS







NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
2. PLATING: Cu 15 TO 20 MICROMETERS
   Ni 10 ± 5 MICROMETERS
   Au 1 ± 0.5 MICROMETER
3. REFERENCE JEDEC MO-209, VARIATION HDBH, DATED SEPTEMBER 1998.

APPROVALS	DATE
DRAWN T. LEQUANG	01/31/2000
DFTG. CHK. MARTA SUCHY	01/31/2000
ENGR. CHK. WAYNE LEE	01/31/2000

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

CSP, PLASTIC, LAMINATED, 8.1x12.5x1.0mm BODY, 2X THERMAL PAD, 48 L, 0.5mm PITCH

PROJECTION INCH [MM]

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	(SC)MKT-SLB48C	A

FORMERLY: N/A SHEET 1 of 1